

Product Advisory

Issue Date: 12-December-2022

Change Description:

1. Qualify 2nd manufacturing site for backside metallization process
2. Introduction of wafer test at contract manufacturer

Parts Affected:

AFBR-S4N66P024M
AFBR-S4N44P164M

Description and Extent of Change:

- 1. Qualify 2nd manufacturing site for backside metallization**
Qualify second source manufacturing site outside of Germany for above stated products to comply with customer request for assurance of supply.
- 2. Introduction of wafer test at contract manufacturer**
Current wafer test is performed at Broadcom site. Qualify additional wafer test at contract manufacturer outside of Germany to comply with customer demand.

Reasons for Change:

Increase production capacity and assurance of supply for above mentioned products.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

No change of fit, form or functionality. The product datasheet specifications remain the same. Reliability qualifications have been performed to ensure product reliability and are available on request. Buyoff tests have been performed successfully.

Effective Date of Change:

Product shipments using this change will begin on or after 16-January-2023. Timing of shipment of the changed part will vary by part number depending on customer demand and inventory levels.

Please contact your Broadcom field sales engineer or Contact Center for any questions or support requirements. Please acknowledge the receipt of the notice within 30 days of delivery. Lack of acknowledgement within 30 days constitutes acceptance of the change per JEDEC J-STD-046.